TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (MACHII π -MOSVI)

2SK3911

Switching Regulator Applications

• Small gate charge: Qg = 60 nC (typ.)

- Low drain-source ON resistance: RDS (ON) = 0.22Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current: $IDSS = 500 \mu A (VDS = 600 V)$
- Enhancement model: $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristic			Symbol	Rating	Unit	
Drain-source voltage			V_{DSS}	600	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V_{DGR}	600	V	
Gate-source voltage			V_{GSS}	±30	V	
Drain current	DC (f	Note 1)	I _D	20	А	
	Pulse (I	Note 1)	I_{DP}	80		
Drain power dissipation (Tc = 25°C)			P _D	150	W	
Single pulse avalanche energy (Note 2)			E _{AS}	792	mJ	
Avalanche current			I _{AR}	20	Α	
Repetitive avalanche energy (Note 3)			E _{AR}	15	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T _{stg}	-55~150	°C	

Unit: mm 15.9 max 03.2±0.2 00 1.0±0.3 1.0±0.3 1.0±0.3 1. Gate 2. Drain (heatsink) 3. Source JEDEC JEITA SC-65 TOSHIBA 2-16C1B

Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristic	Symbol	Max	Unit	
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W	
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W	

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 3.46 mH, $I_{AR} = 20 \text{ A}$, $R_G = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

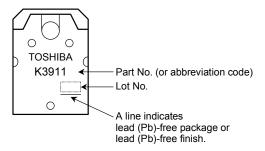
Electrical Characteristics (Ta = 25°C)

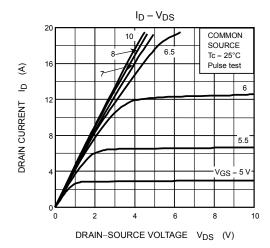
Char	acteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Gate-source brea	akdown voltage	V (BR) GSS	$I_D = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cutoff curre	ent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	500	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 10 A	_	0.22	0.32	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 10 A	3.0	11	_	S
Input capacitance		C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	4250	_	pF
Reverse transfer capacitance		C _{rss}		_	10	_	
Output capacitance		C _{oss}		_	420	_	
Switching time	Rise time	t _r	V_{GS} $V_{DD} \simeq 200 \text{ V}$	_	12	_	ns
	Turn-on time	t _{on}		_	45	_	
	Fall time	t _f			12		
	Turn-off time	t _{off}	Duty \leq 1%, $t_W = 10 \mu s$	_	80		
Total gate charge		Qg		_	60	_	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	_	50	_	nC
Gate-drain charge		Q _{gd}		_	10	_	

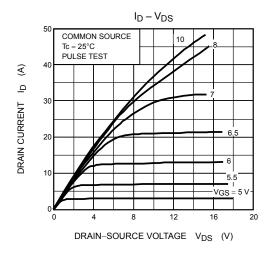
Source-Drain Ratings and Characteristics (Ta = 25°C)

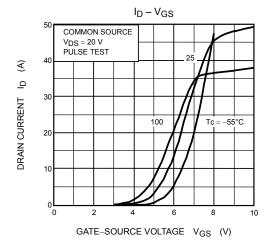
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_		_	20	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	80	Α
Forward voltage (diode)	V _{DSF}	$I_{DR} = 20 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 20 \text{ A}, V_{GS} = 0 \text{ V},$	_	1350	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs	_	24	_	μС

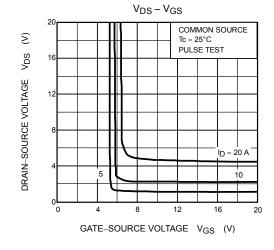
Marking

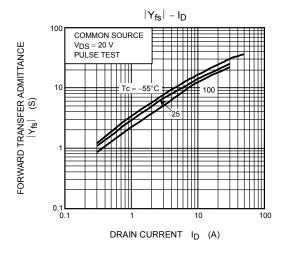


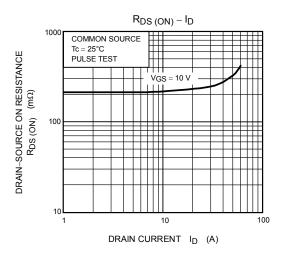


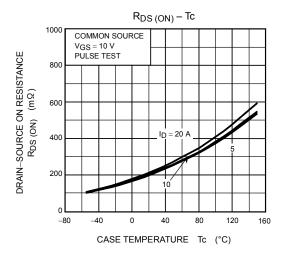


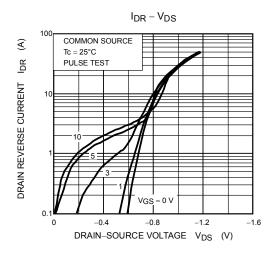


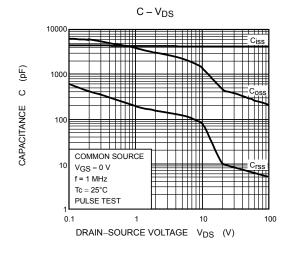


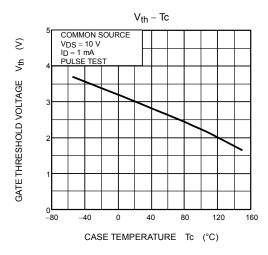


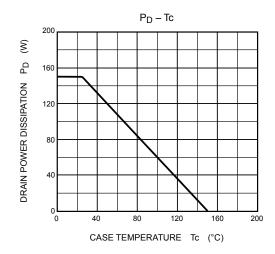


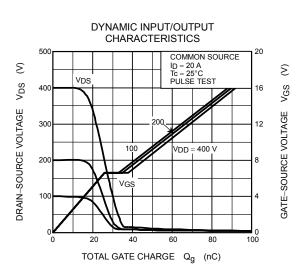




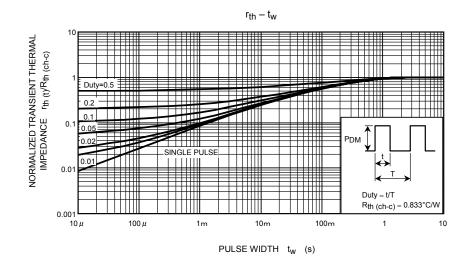


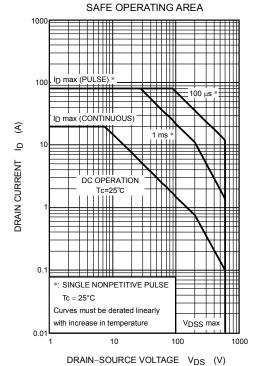


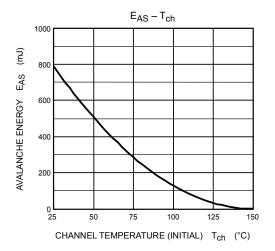


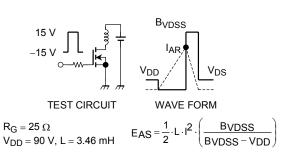


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